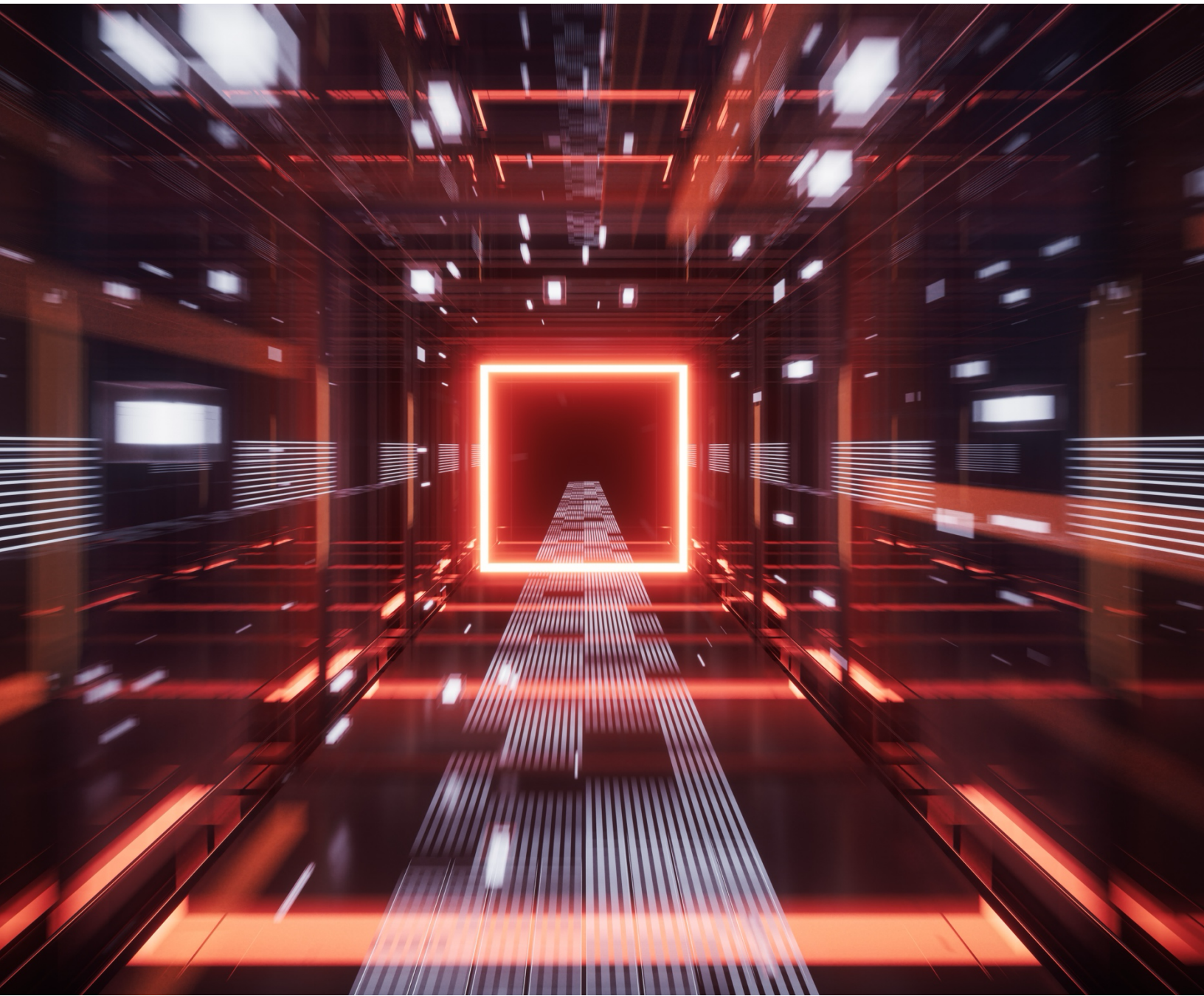




Corporate Background



At a Glance

Founded
2026

Headquarters
San Jose, CA

Industry
Semiconductors/
AI Infrastructure

Funding
\$43M

Key Executives
Mohit Gupta
Sunil Bhardwaj



Company Overview

As the industry's first pure-play, standards-based chiplet platform company, TYLsemi™ has redefined how chiplet-enabled custom silicon is built by providing AI infrastructure customers with a faster, lower-risk path from architecture to deployment. Delivering a full portfolio of chiplets across connectivity, power and memory, TYLsemi enables customers to integrate proven silicon building blocks instead of designing critical components from scratch, accelerating development and reducing time-to-market. This industry first approach drives down development time and cost for AI infrastructure silicon by nearly 50% and includes full ecosystem enablement for high-volume manufacturing.

TYLsemi's chiplet portfolio is purpose-built as the foundation for full custom silicon — enabling customers to assemble complete, production-ready systems from proven, pre-validated building blocks.

By replacing fragmented IP, design, and manufacturing workflows with a single, accountable delivery model, TYLsemi eliminates integration risk and delivers a predictable path from architecture to deployment.

Customers and Market

AI systems are shifting from monolithic chips to distributed, multi-die architectures as chip size approaches physical limits. Advances in packaging technologies and the emergence of standardized interconnects such as UCIe are making chiplet-based design practical and scalable.

TYLsemi targets the fastest-growing segments of AI infrastructure silicon, including:

- Hyperscaler and AI infrastructure architecture teams designing next-generation data center systems
- Custom silicon and ASIC design teams requiring a faster, lower-risk path to production
- System and SoC architects managing the transition from monolithic to chiplet-based designs
- Companies building sovereign AI infrastructure that require a non-captive silicon partner

AI-driven silicon is projected to exceed \$80B by 2030, with chiplets representing the fastest-growing segment and custom silicon — built on chiplet foundations — emerging as the dominant design approach for next-generation AI infrastructure. The market is structurally underserved: Hyperscalers are captive, large merchant vendors are misaligned with emerging customers, and existing alternatives deliver only fragments of a complete solution. TYLsemi fills this gap.

Technology

TYLsemi delivers UCIe-native, standards-based chiplets built specifically to simplify AI infrastructure design. Unlike IP providers or design services firms. The company provides production-ready silicon that customers can integrate directly into real system architectures.

Key technology differentiators include:

- Standards-based architecture built on standards-based connectivity IP for broad ecosystem interoperability
- Pre-validated, KGD-screened silicon — not just IP or design components
- Modular, reusable chiplet foundation that supports both standalone integration and full custom silicon
- Deep packaging and supply chain integration across TSMC and leading OSAT partners
- Proven execution: founders with \$1B+ in orders, 30M+ chips shipped, and 75+ high-volume designs

TYLsemi's approach eliminates the fragmentation of traditional semiconductor development, replacing disconnected tools, IP, and services with a single, accountable delivery model. Customers move from architecture to deployment with confidence, leveraging validated components and predictable execution.

Products

TYLsemi offers a portfolio of standards-based chiplets and an integrated platform for custom silicon delivery:

Product	Description	Key Capabilities
TYLIO™	Versatile connectivity chiplet product family for AI systems.	Comprehensive family of connectivity IO chiplets designed to enable high-bandwidth, standards-based connectivity across high-performance systems supporting PCIe, ESUN, and UALink connectivity today, with a co-packaged optics (CPO) roadmap for next-generation rack-scale fabrics.
TYLPower™	Intelligent In-package power delivery solution for multi-die systems.	An integrated voltage regulator (IVR) chiplet that provides efficient and intelligent control for optimized system-level power efficiency.
TYLMem™	Versatile memory connectivity and expansion product family for AI systems.	A planned product family focused on memory connectivity for advanced AI systems, with additional details to be announced as the roadmap progresses.
TYLForge™	End-to-end chiplet enabled silicon platform.	TYLForge integrates TYLsemi's full chiplet portfolio — IO, power, and memory — with custom compute and fabric chiplets, plus end-to-end platform solutions spanning architecture, IP, foundry, advanced packaging, and supply chain integration. The result is a complete, production-ready custom silicon system — delivered with the speed and predictability that only a purpose-built chiplet foundation can provide.



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